



Materials Declaration Form

IPC Form Type *	1752 Distribute	Version	2
Sectionals *	Material Info Manufacturing Info	Subsectionals *	A-D <i>* : Required Field</i>

Supplier Information			
Company Name *	STMicroelectronics	Response Date *	2016-09-12
Contact Name *	Refer to Supplier Comment section		Refer to Supplier Comment section
Authorized Representative *	Floriana San Biagio	Representative Title	AMG MD CHAMPION
Representative Phone *	Refer to Supplier Comment section	Representative Email *	Refer to Supplier Comment section
Supplier Comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty Statement


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Legal Statement			
Supplier Acceptance *	true	Legal Declaration *	Standard

Legal Statement

Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.

Product				
Mfr Item Number	Mfr Item Name	Version	Mfr Site	Date
	4YNB*0393BG6	A	Z6HA	2016-09-12
Amount	UoM	Unit type	ST ECOPACK Grade	
8.07	mg	Each	ECOPACK® 3	

Manufacturing information				
J-STD-020 MSL Rating	Classification Temp	Nbr of Reflow Cycles		 life.augmented
1	260	3		
bulk Solder Termination	Terminal Plating	Terminal Base Alloy	Comment	
Not Applicable ; if coating is used o	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy		

Package Designator	Size	Nbr of instances	Shape	
QFN	2x2x0.6	8	No lead	
Comment	Package: NB UFSON 2x2x0.6 8 PITCH 0.5; MDF valid for LM2903Q2T			

QueryList : ROHS directive 2011/65/EU _ July 2011	
Query	Response
1 - Product(s) meets EU RoHS requirement without any exemptions	true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)	false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)	false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions	false
5 - Product(s) is obsolete, no information is available	false
6 - Product(s) is unknown, no information is available	false
Exemption Id.	Description

QueryList : REACH-20th June 2016				
Query				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product

Material Composition Declaration						Mfr Item Name	4YNB*0393BG6					
Homogeneous Material	Material Group	Mass	UoM	Level	Substance Category	Substance	CAS	Exempt	Mass	UoM	Concentration in homogeneous material (ppm)	Concentration in product (ppm)
Die	Other inorganic materials	0.298	mg	supplier	die	Silicon (Si)	7440-21-3		0.289	mg	969799	35812
				supplier	metallization	Aluminium (Al)	7429-90-5		0.004	mg	13423	496
				supplier	Passivation	Silicon Nitride	12033-89-5		0.002	mg	6711	248
				supplier	Passivation	Silicon Oxide	7631-86-9		0.003	mg	10067	372
Leadframe	Copper & its alloys	3.050	mg	supplier	alloy	Copper (Cu)	7440-50-8		2.865	mg	939344	355019
				supplier	alloy	Silicon (Si)	7440-21-3		0.016	mg	5246	1983
				supplier	alloy	Nickel (Ni)	7440-02-0		0.105	mg	34426	13011
				supplier	alloy	Magnesium (Mg)	7439-95-4		0.004	mg	1311	496
				supplier	alloy	Iron (Fe)	7439-89-6		0.003	mg	984	372
				supplier	alloy	Zinc (Zn)	7440-66-6		0.016	mg	5246	1983
				supplier	alloy	Manganese (Mn)	7439-96-5		0.002	mg	656	248
				supplier	metallization	Nickel (Ni)	7440-02-0		0.035	mg	11475	4337
				supplier	metallization	Palladium (Pd)	7440-05-3		0.003	mg	984	372
				supplier	metallization	Gold (Au)	7440-57-5		0.001	mg	328	124
Die attach	Other inorganic materials	0.117	mg	supplier	glue	Epoxyde Bisphenol A Resin	25068-38-6		0.011	mg	94017	1363
				supplier	glue	Silica, vitreous	60676-86-0		0.035	mg	299145	4337
				supplier	glue	Ethoxyethoxy-ethyl Acetate	112-15-2		0.025	mg	213675	3098
				supplier	glue	Aluminium oxide	1344-28-1		0.024	mg	205128	2974
				supplier	glue	Bisphenol A diglycidyl ether polymer	25036-25-3		0.017	mg	145299	2107
				supplier	glue	Glycol ether ester	Proprietary		0.002	mg	17094	248
				supplier	glue	Diaminodiphenylsulfone	80-08-0		0.002	mg	17094	248
				supplier	glue	Aminopropyltriethoxysilane	919-30-2		0.001	mg	8547	124
Bonding wire	Precious metals	0.161	mg	supplier	wire	Gold (Au)	7440-57-5		0.161	mg	1000000	19950
encapsulation	Other inorganic materials	4.034	mg	supplier	mold compound	Silica Fused	60676-86-0		3.534	mg	876054	437918
				supplier	mold compound	Epoxy Resin	85954-11-6		0.238	mg	58999	29492
				supplier	mold compound	Phenol Resin	26834-02-6		0.238	mg	58999	29492
				supplier	mold compound	Carbon Black	1333-86-4		0.024	mg	5949	2974
Finishing	Other inorganic materials	0.408	mg	supplier	connection coating	Tin (Sn)	7440-31-5		0.408	mg	1000000	50558